

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:
Chii-Ming WU, et al.

Serial No.: 10/657,505

Filed: September 8, 2003

For: Method of Manufacturing a Contact
Interconnection Layer Containing a Metal and
Nitrogen by Atomic Layer Deposition for Deep
Sub-Micron Semiconductor Technology

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Confirmation No. 9336

Group Art Unit: 2812

Examiner: Geyer, Scott B.

Attorney Docket No.:
TS01-1247 / 24061.406

Commissioner for Patents
Mail Stop Amendment
P.O. Box 1450
Alexandria, VA 22313-1450

Certificate of Service

I hereby certify that this correspondence is being filed with
the U.S. Patent and Trademark Office via EFS-Web on
July 27, 2006.


Linda Ingram

AMENDMENT

Sir:

The Commissioner is hereby authorized to charge any fees required for entry of this paper,
including those for any extensions of time, to Haynes and Boone LLP's Deposit Account No. 08-1394.
Applicants are enclosing a Petition for a one-month time extension.

In response to the Office Action of April 3, 2006, please amend the above-identified application as
follows:

Amendments to the Claims are reflected in the listing of claims which begins on **page 2** of this paper.

Remarks begin on **page 7** of this paper.